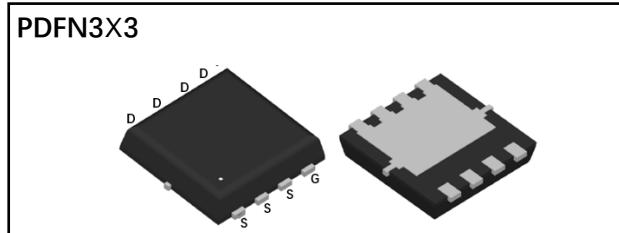


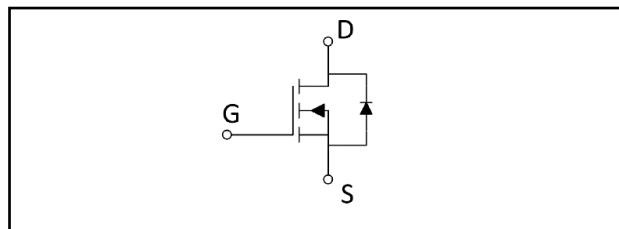
Nch 40V 50A Power MOSFET

V_{DS}	40V
R_{DS(ON)} (typ.)	4.5mΩ
I_D	50A
P_D	40W

Outline



Inner Circle



Packaging specifications

Packing	Embossed Tape
Reel Size(mm)	330
Tape width(mm)	12
Basic ordering unit (pcs)	5000
Taping code	D3
Marking	AD40N50D3

Features

- 1、Low on – resistance
- 2、High power package (PDFN3X3)
- 3、Pb-free lead plating ; RoHS compliant
- 4、Halogen free
- 5、100% Rg and UIS tested

Applications

Switching

Absolute maximum ratings (T_c=25°C)

Symbol	Parameter	Value	Unit
V _{DS}	Drain-Source Voltage (V _{GS} =0V)	40	V
V _{GS}	Gate-Source Voltage (V _{GS} =0V,static)	±20	V
I _D	Continuous Drain Current (T _c =25°C)	50	A
	Continuous Drain Current (T _c =100°C)	32	A
I _{DM}	Pulsesd Drain Current	200	A
I _{AS}	Avalanche Current (L=0.1mH)	22	A
E _{AS}	Single Pulsed Avalanche Energy	24	mJ
P _D	Maximum Power Dissipation (T _c =25°C)	40	W
	Power Dissipation – Derate above 25°C	0.32	W/°C
T _J , T _{STG}	Operating,Storage Temperature Range	-55~150	°C

Symbol	Parameter	Max.	Unit
R _{θJA}	Thermal Resistance,Junction-to-Ambient	63	°C/ W
R _{θJC}	Thermal Resistance,Junction-to-Case	3.1	°C/ W

Electrical Characteristics (TJ=25°C, unless otherwise noted)

Static State Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
B _{VDSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	40	---	---	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =40V, V _{GS} =0V	---	---	1	μA
I _{GSS}	Gate -Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
R _{DS(ON)}	Drain-Source On-stage Resistance	V _{GS} =10V, I _D =4A	---	4.5	5.6	mΩ
		V _{GS} =4.5V, I _D =3A	---	7.1	8.8	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D =250μA	1.2	1.6	2.4	V
g _f	Forward Transconductance	V _{DS} =10V , I _S =1A	---	4	---	S

Dynamic Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Q _g	Total Gate Charge	V _{DS} =20V V _{GS} =10V I _D =20A	---	14	---	nC
Q _{gs}	Gate Source Charge		---	3	---	
Q _{gd}	Gate Drain Charge		---	6	---	
t _{d(on)}	Turn-on delay Time	V _{DS} =20V V _{GS} =10V R _G =6Ω I _D =20A	---	10	---	ns
t _r	Rise time		---	14	---	
t _{d(off)}	Turn-off delay Time		---	28	---	
t _f	Fall time		---	20	---	
C _{iss}	Input capacitance	V _{DS} =20V V _{GS} =0V f=1MHz	---	790	---	pF
C _{oss}	Output capacitance		---	350	---	
C _{rss}	Reverse transfer capacitance		---	20	---	
R _g	Gate Resistance	f=1MHz	---	1.5	---	Ω

Drain-Source Diode Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I _s	Continuous Source Current	V _{DS} =V _{GS} =0V Force Current	---	---	50	A
I _{SM}	Pulsed Source Current		---	---	100	A
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _s =1A	---	---	1.0	V
t _{rr}	Reverse Recovery Time	V _{GS} =0V, I _s =1A di/dt=200A/μs	---	13	---	ns
Q _{rr}	Reverse Recovery Charge		---	25	---	nC

Electrical Characteristics Diagrams

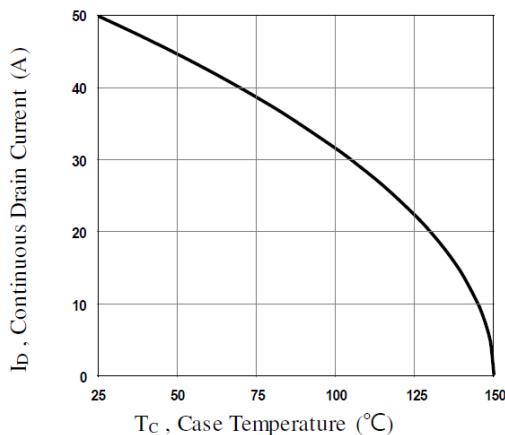


Figure 1. Continuous Drain Current vs. T_c

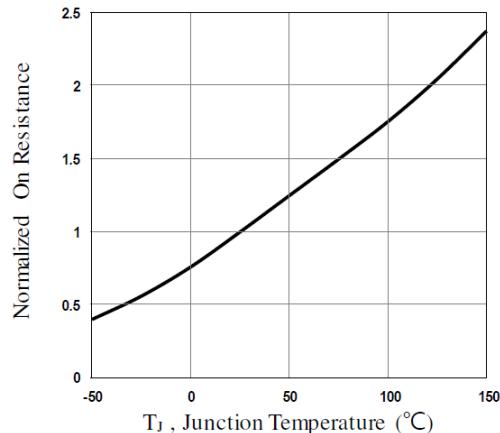


Figure 2. Normalized R_{DS(ON)} vs. T_j

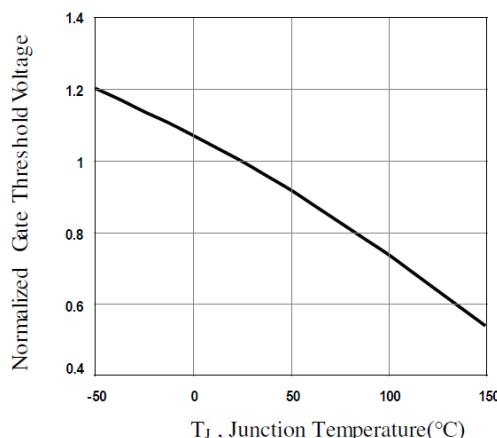


Figure 3. Normalized V_{th} vs. T_j

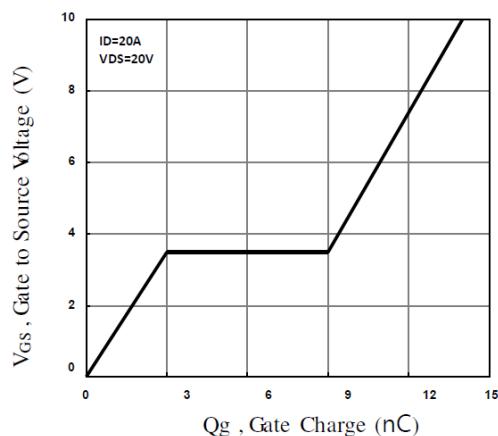


Figure 4. Gate Charge Waveform

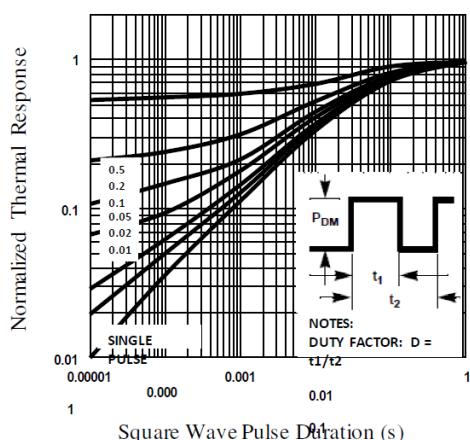


Figure 5. Normalized Transient Impedance

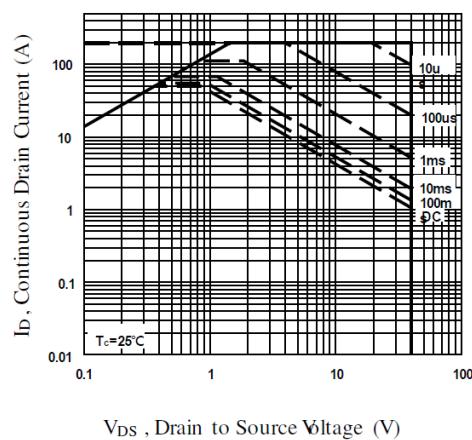
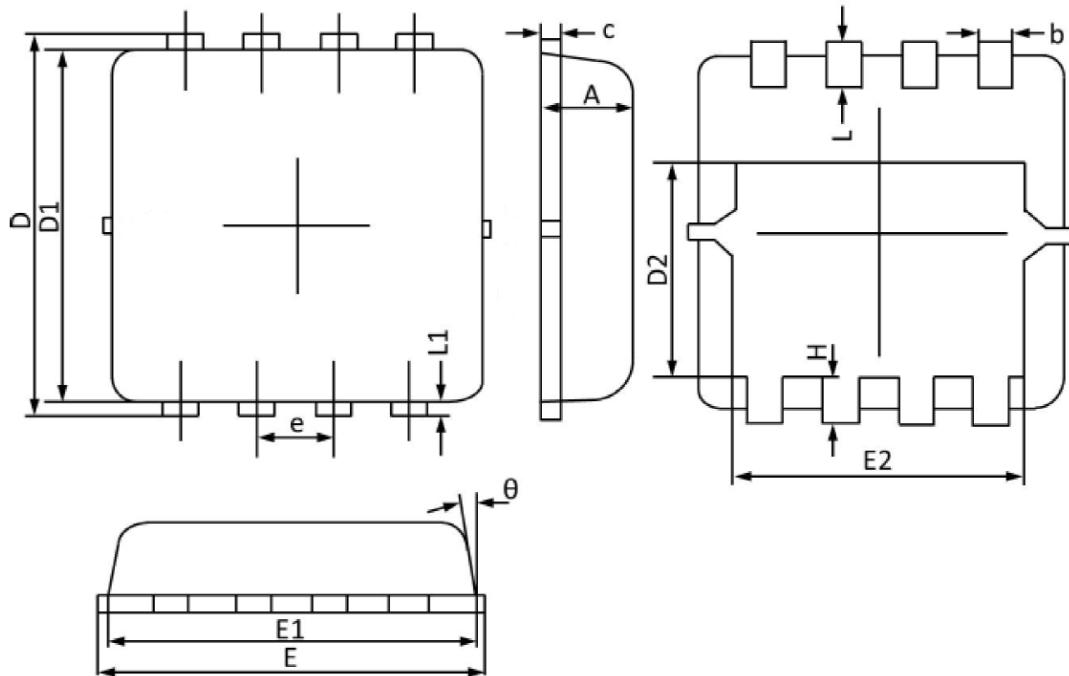


Figure 6. Maximum Safe Operation Area

PDFN3X3 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	0.900	0.700	0.035	0.028
b	0.350	0.240	0.014	0.009
c	0.250	0.100	0.010	0.004
D	3.450	3.050	0.136	0.120
D1	3.200	2.900	0.126	0.114
D2	1.850	1.350	0.073	0.053
E	3.400	3.000	0.134	0.118
E1	3.250	2.900	0.128	0.114
E2	2.600	2.350	0.102	0.093
e	0.65BSC		0.026BSC	
H	0.500	0.300	0.020	0.012
L	0.500	0.300	0.020	0.012
L1	0.200	0.070	0.008	0.003
θ	12°	0°	12°	0°